REFERENCE

1. Application

This specification applies to the outline and characteristics of OPIC light detecting device Model No. GA220T2L1IZ.

2. Outline

Refer to the attached drawing No. CY11648L02.

3. Ratings and characteristics

Refer to the attached sheet, page 4, 5.

4. Reliability

Refer to the attached sheet, page 6.

5. Outgoing inspection

Refer to the attached sheet, page 7.

6. Supplement

(6-1) Circuit block diagram

Refer to the attached sheet, page 9.

(6-2) Packing specifications shall be referred to attached drawing.
Packing materials of this model are used materials excepting corrugated cardboard materials.
Regarding disposal of this packing materials, please handle with care.

(6-3) This product is not designed against electromagnetic and ionized-particle irradiation.

(6-4) This product shall not contain the following materials.
Also, the following materials shall not be used in the production process for this product.
Materials for ODS : CFC_S, Halon, Carbon tetrachloride
1.1.1-Trichloroethane (Methyl chloroform)

(6-5) Product mass (Piece) : Approximately 117mg

7. Notes

(7-1) By-pass capacitors

In order to stabilize power supply line, connect some by-pass capacitors of 0.01 to 0.1 μF between Vcc and GND within 1cm from lead pins.

(7-2) Cleaning conditions :

Solvent cleaning : Solvent temperature 45℃ or less Immersion for 3 min or less

Ultrasonic cleaning : The effect to device by ultrasonic cleaning differs by cleaning bath size, ultrasonic power output, cleaning time, PCB size or device mounting condition etc.
Please test it in actual using condition and confirm that doesn't occur any defect before starting the ultrasonic cleaning.
The cleaning shall be carried out with solvent below.
Solvent : Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

(7-2) Soldering

(1) Solder reflow

Temperature profile etc. is set up later.

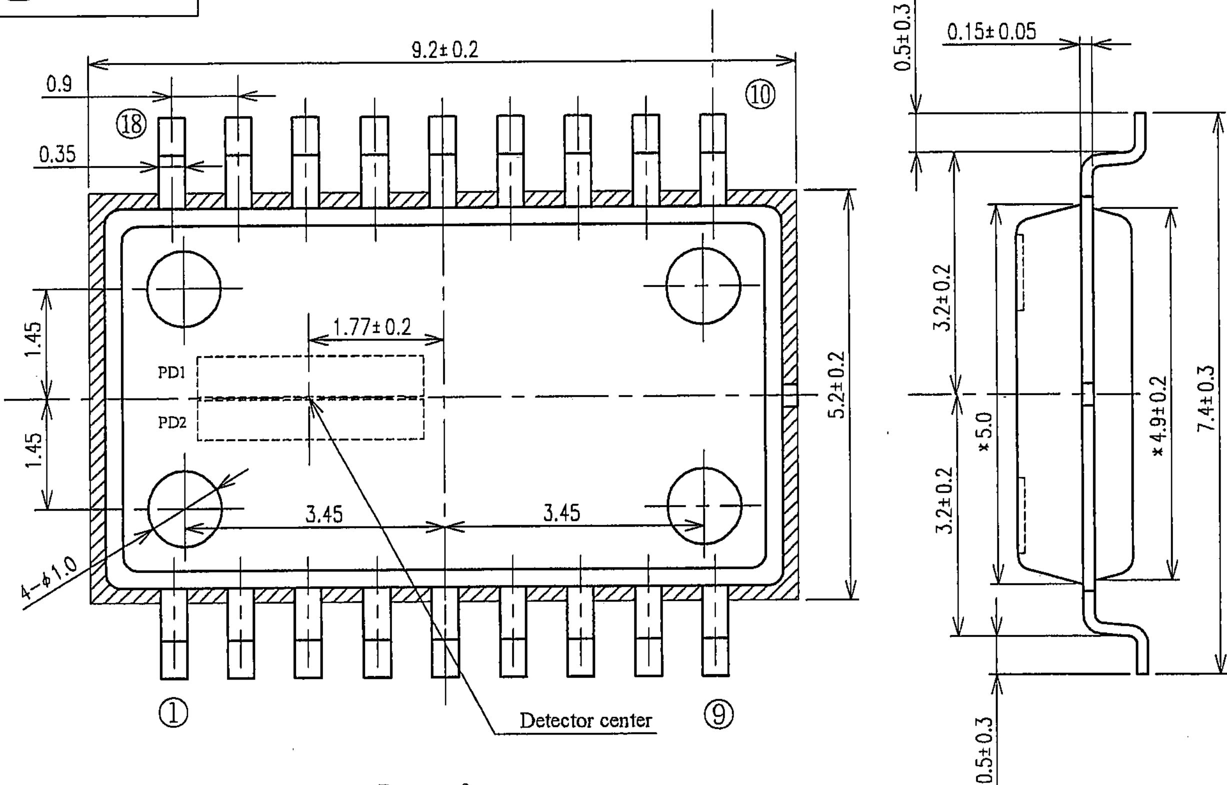
(2) Soldering by hand

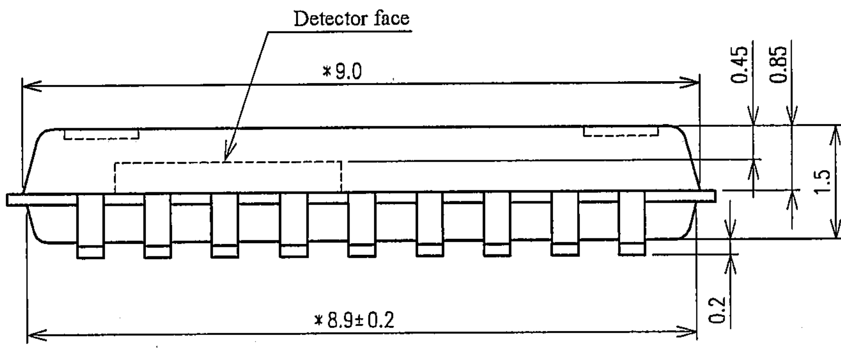
To solder onto lead pins, please solder at 260℃ for 3 seconds or less.
Please be careful not to give the mechanical stress to the package when soldering because it may cause the deformation or defect due to the plated connection.

(3) Case of other soldering

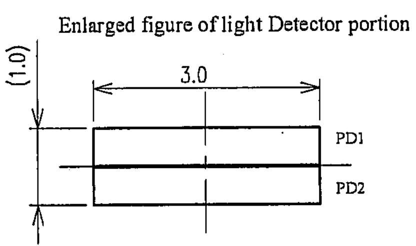
Other soldering methods such as dip soldering and VPS shall not be used.
Please use (1) and (2).

SHARP





Enlarged figure of light Detector portion



1) Unspecified tolerance shall be ±0.1.
2) Dimensions in parenthesis are shown for reference.
3) [hatched]: Burr
4) Resin burr shall not be included in outline dimensions.
5) Package taper : 15°
6) Dimensions of * mark are excluded the parting surface.
7) Chip positioning tolerance : ±0.2
   Chip rotation tolerance : ±3°
8) Lead pin Horizontal tolerance : MAX. 0.15.
   Vertical tolerance : MAX. 0.2.

Pin arrangement

Pin	Function	Pin	Function
①	Vcc1	⑩	Vo
②	Vcc1	⑪	GND
③	Vcc1	⑫	Ro1
④	Vcc1	⑬	Vcc2
⑤	[IN (PD2)]	⑭	[IN (PD1)]
⑥	Ro2	⑮	Vcc1
⑦	GND	⑯	Vcc1
⑧	Vext	⑰	Vcc1
⑨	GND	⑱	Vcc1

Scale	Material	Finish	Name	GA220T2L1IZ Outline Dimensions
10/1	Lead : 42 Alloy	Lead pin: Solder dip		
Unit	Package : Epoxy resin	(Lead-free solder use Composition(Standard value) Sn96.5%,Ag3.0%,Cu0.5%)	Drawing No.	CY11648L02
1 = 1/1 mm				